can be applied along the smooth surface 502 of wafer 504, as shown in Fig. 8. Thermal transducers 500 are located on rails 506 contoured onto surface 502. Representative rails 506 are noted in Fig. 8. As shown in FIG. 10, the thermal transducers 500 can be covered with a protective layer 516, such as diamond-like carbon. Additional transducers such as a piezoelectric transducer also can be placed on the opposite surface of the wafer prior to the slicing into individual sliders.

IN THE CLAIMS

Please amend claims 2, 4, 6, 12-13, 15-16, 18, 21, 23 and 25-26 as follows:

2.(Thrice Amended) A glide head comprising:

a glide body including a leading edge, a trailing edge and a raised bearing surface; and

at least one thermal transducer formed on the raised bearing surface having a surface portion extending along a portion of the raised bearing surface and a thickness portion intersecting the surface portion extending along the portion of the raised bearing surface to form a glide interface to detect asperities.

4.(Twice Amended) The glide head of claim 2 wherein the raised bearing surface includes opposed side rails oriented along a length of the glide body and the at least one thermal transducer is formed along a portion of a length of at least one of the opposed side rails.

6.(Twice Amended) The glide head of claim 2 wherein the at least one thermal transducer is in electrical contact with electrically conductive pads proximate to the trailing edge of the glide body.

12.(Twice Amended) The glide head of claim 11 wherein the

plurality of thermal transducers comprise a first thermal transducer and a second thermal transducer and the first and second thermal transducers share a common electrical ground.

13. (Twice Amended) The glide head of claim 11 wherein the plurality of thermal transducers are spaced along the raised bearing surface and the glide head further comprises electrically conductive strips in electrical contact with the plurality of thermal transducers, the strips being formed on a recessed bearing surface offset from the raised bearing surface.

15. (Twice Amended) The glide head of claim 2 in combination with a glide test system.

16. (Fourth Amended) A method of fabricating a glide head comprising:

fabricating a raised bearing surface and a recessed surface; and

depositing a thermal transducer on the raised bearing surface to form a glide interface to detect asperities.

18. (Thrice Amended) A method of fabricating a glide head from a wafer comprising;

slicing a plurality of glide bodies from the wafer; and

depositing thermal transducers on the plurality of glide bodies sliced from the wafer.

21. (Twice Amended) The method of claim 18 and further comprising:

fabricating an air bearing on the plurality of glide bodies sliced from the wafer including a raised bearing surface and a recessed bearing surface prior to depositing the thermal transducers; and

depositing the thermal transducers on the raised bearing

surfaces of the plurality of glide bodies sliced from the wafer.

23. (Amended) The glide head of claim 2 including a plurality of spaced thermal transducers spaced along a length of the glide body between the leading edge and the trailing edge of the glide body.

25. (Amended) A glide head comprising:

a glide body including a leading edge, a trailing edge and a raised bearing surface and a recessed bearing surface; and

asperity detection means on the glide body for detecting asperities on a disc surface.

26. (Amended) The method of claim 16 wherein the step of fabricating the raised bearing surface and the recessed surface and the deposition of the thermal transducer is performed on a surface of a wafer prior to slicing a plurality of glide heads from the wafer.

Please add new claim 27 as follows:

27. (New) A head comprising:

a body portion including a leading edge, a trailing edge and a raised bearing surface extending along a portion of a length of the body portion between the leading edge and the trailing edge; and

at least one thermal transducer formed on the raised bearing surface.